



OCT 03 2007

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as First Class Mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: September 27, 2007

Signature:

(Rabiyah S. Kader)
EXPEDITED PROCEDURE

Group Art Unit: 2814

Docket No.: TIMI 3.0-003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

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Iijima et al.

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Application No.: 10/812,349

: Group Art Unit: 2814

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Filed: March 30, 2004

: Examiner: T. X. Le

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For: WIRING CIRCUIT BOARD,
 MANUFACTURING METHOD FOR THE
 WIRING CIRCUIT BOARD, AND
 CIRCUIT MODULE

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RESPONSE UNDER 37 CFR 1.116

MS AF
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated April 27, 2007, finally rejecting claims 52-59, please amend the above-identified U.S. patent application as follows: